



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD50R399CP		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA000909390						
<b>Package</b>		PG-TO252-3-341		<b>Weight*</b>		383.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.846	1.26	1.26	12625	12625
leadframe	non noble metal	iron	7439-89-6	0.248	0.06		647	
	inorganic material	phosphorus	7723-14-0	0.075	0.02		194	
	non noble metal	copper	7440-50-8	248.124	64.64	64.72	646436	647277
wire	non noble metal	aluminium	7429-90-5	4.362	1.14	1.14	11364	11364
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.652	0.43		4304	
	plastics	brominated resin	-	1.770	0.46		4611	
	organic material	carbon black	1333-86-4	1.888	0.49		4918	
	plastics	epoxy resin	-	15.928	4.15		41498	
	inorganic material	silicondioxide	60676-86-0	96.750	25.21	30.74	252062	307393
leadfinish	non noble metal	tin	7440-31-5	3.787	0.99	0.99	9866	9866
plating	non noble metal	nickel	7440-02-0	0.515	0.13	0.13	1342	1342
solder	noble metal	silver	7440-22-4	0.097	0.03		253	
	non noble metal	tin	7440-31-5	0.078	0.02		203	
	non noble metal	lead	7439-92-1	3.714	0.97	1.02	9677	10133
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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